

P-Channel 12-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$ $I_D($				
	0.0050 at V _{GS} = - 4.5 V	- 16			
- 12	0.0065 at V _{GS} = - 2.5 V	- 15			
	0.0100 at V _{GS} = - 1.8 V	- 13			

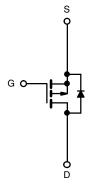
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- Compliant to RoHS Directive 2002/95/EC

Pb-free ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- · Load Switch
- · Battery Switch



P-Channel MOSFET

	SO-8		
S 1 S 2 S 3		8 7 6	D D D
G 4		5	D
	Top View		

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unle	ss otherwise n	oted		
Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	- 12		V
Gate-Source Voltage		V _{GS}	± 8		
Continuous Dusin Comment /T 150 °C)	T _A = 25 °C	- I _D	- 16	- 10	Δ.
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C		- 11.5	- 8	
Pulsed Drain Current		I _{DM}	- 50		Α
Continuous Source Current (Diode Conduction) ^a		I _S	- 2.7	- 1.36	
Maniana Bana Birahating	T _A = 25 °C	P _D	3.0	1.5	W
Maximum Power Dissipation ^a	T _A = 70 °C		1.9	0.95	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^a	t ≤ 10 s	R	33	42		
	Steady State	- R _{thJA}	70	84	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	16	21		

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

1



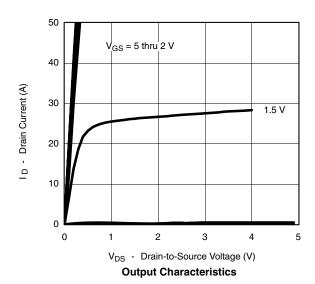
Parameter	Symbol	Test Conditions Mir		Тур.	Max.	Unit	
Static							
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -600 \mu\text{A}$ - 0.5 - 1.0		1.0	V		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$		± 100		nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 12 V, V _{GS} = 0 V			- 1	μΑ	
		$V_{DS} = -12 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 70 ^{\circ}\text{C}$			- 10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 30			Α	
		V _{GS} = - 4.5 V, I _D = - 14 A		0.0050			
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 13 A		0.0065		Ω	
		V _{GS} = - 1.8 V, I _D = - 12 A		0.0100			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 6 V, I _D = - 14 A 80			S		
Diode Forward Voltage ^a	V_{SD}	I _S = - 2.7 A, V _{GS} = 0 V - 0.6		- 1.1	٧		
Dynamic ^b							
Total Gate Charge	Q_g			110	165		
Gate-Source Charge	Q_{gs}	$V_{DS} = -6 \text{ V}, V_{GS} = -5 \text{ V}, I_{D} = -14 \text{ A}$		15		nC	
Gate-Drain Charge	Q_{gd}			27.5		1	
Turn-On Delay Time	t _{d(on)}			110	170		
Rise Time	t _r	V_{DD} = - 6 V, R_L = 6 Ω		235	350		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ - 1 A, V_{GEN} = - 4.5 V, R_g = 6 Ω		410	620	ns	
Fall Time	t _f			285	430		
Gate Resistance	R_g			3.6		Ω	
Source-Drain Reverse Recovery Time t _{rr}		I _F = - 2.1 A, dl/dt = 100 A/μs		180	270	ns	

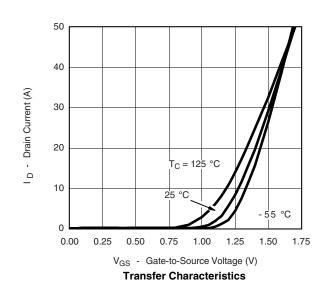
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

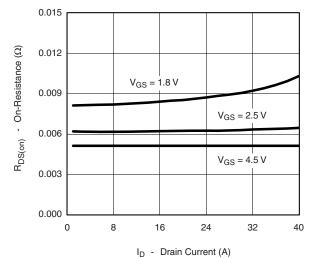
TYPICAL CHARACTERISTICS 25 °C unless otherwise noted



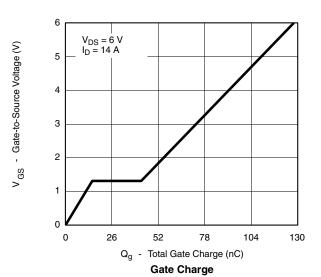




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On-Resistance vs. Drain Current



T_J = 150 °C

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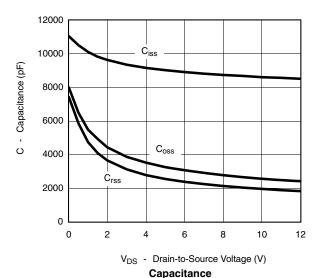
T_J = 25 °C

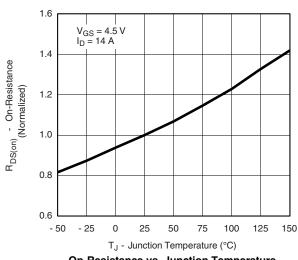
T_J = 25 °C

V_{SD} - Source-to-Drain Voltage (V)

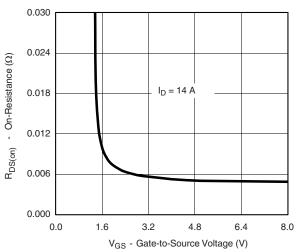
Source-Drain Diode Forward Voltage

30





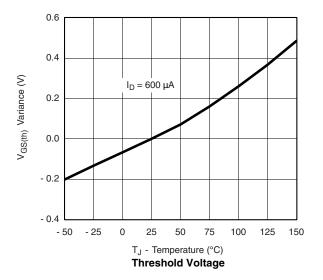
On-Resistance vs. Junction Temperature

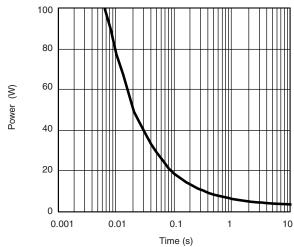


On-Resistance vs. Gate-to-Source Voltage

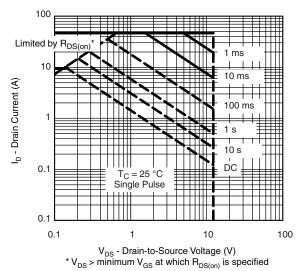


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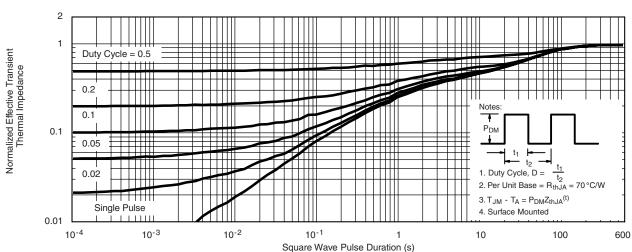




Single Pulse Power, Junction-to-Ambient



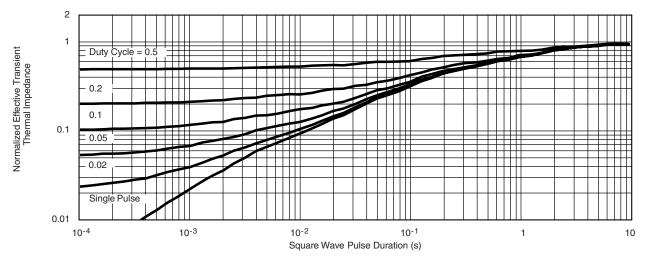




Normalized Thermal Transient Impedance, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot



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